

136243

SEARCH REQUEST FORM Scientific and Technical Information Center - EIC2800
 Rev. 3/15/2004 This is an experimental format -- Please give suggestions or comments to Jeff Harrison, JEF-4B68, 272-2511.

Date 10/26/04 Serial # 10/07,737 Priority Application Date _____
 Your Name M. Lewis Examiner # _____
 AU 9822 Phone 272-1838 Room 5A30
 In what format would you like your results? Paper is the default. PAPER DISK EMAIL

If submitting more than one search, please prioritize in order of need.

The EIC searcher normally will contact you before beginning a prior art search. If you would like to sit with a searcher for an interactive search, please notify one of the searchers.

Where have you searched so far on this case? 10-26-04 P05:13
 Circle: USPT DWPI EPO Abs JPO Abs IBM TDB
 Other: _____

What relevant art have you found so far? Please attach pertinent citations or Information Disclosure Statements. US 2003 003 8355

What types of references would you like? Please checkmark:

Primary Refs _____ Nonpatent Literature _____ Other _____
 Secondary Refs _____ Foreign Patents _____
 Teaching Refs _____

What is the topic, such as the **novelty**, motivation, utility, or other specific facets defining the desired **focus** of this search? Please include the concepts, synonyms, keywords, acronyms, registry numbers, definitions, structures, strategies, and anything else that helps to describe the topic. Please attach a copy of the abstract and pertinent claims.

Claims 1-5, 7-10, 21, 23-26, 28-30

Problem: See pages 1-3
Solution: " " " 4

Staff Use Only
 Searcher: Seatt Harrison
 Searcher Phone: 2-2663
 Searcher Location: STIC-EIC2800, JEF-4B68
 Date Searcher Picked Up: 10/29/04
 Date Completed: 11/1/04
 Searcher Prep/Rev Time: 240
 Online Time: 91

Type of Search
 Structure (#) _____
 Bibliographic ✓
 Litigation _____
 Fulltext _____
 Patent Family _____
 Other _____

Vendors
 STN ✓
 Dialog ✓
 Questel/Orbit _____
 Lexis-Nexis _____
 WWW/Internet _____
 Other _____

File 350:**Derwent WPIX** 1963-2004/UD,UM &UP=200469
 (c) 2004 Thomson Derwent
 File 344:**Chinese Patents Abs** Aug 1985-2004/May
 (c) 2004 European Patent Office
 File 347:**JAPIO** Nov 1976-2004/Jun(Updated 041004)
 (c) 2004 JPO & JAPIO
 File 371:**French Patents** 1961-2002/BOPI 200209
 (c) 2002 INPI. All rts. reserv.
 File 383:**Ei EnCompassPat**(TM) (Ontap)
 (c) 2001 Engineering Info, Inc.

Set	Items	Description
S1	183372	MULTILAYER???? OR (MULTI???? OR STACK???) (2W) (LAYER???? OR LEVEL? ? OR CHIP? ? OR PACKAG???? OR TIER???? OR DIE OR DIES OR DICE) OR MULTILEVEL? ? OR MULTIPACKAG???? OR MCM OR MULTICHIP???????? OR SCSP OR CSP OR CSPS OR PIGGYBACK???? OR OR MCM OR MCMS
S2	2635258	NM OR ANG OR ANG5 OR ANGST? OR THICK? OR THIN? OR MICRON? OR MU OR MUM OR MILLIMICRO? OR MMU OR DIMEN? OR DISTANCE? OR AA OR NANOMET? OR ULTRATHIN? OR SUPERTHIN? OR VERYTHIN? OR NANOTHICK?
S3	2915866	INSULAT???? OR ADHESIV???? OR SPACE???? OR SPACING? ? OR SPACERLESS? OR GAP? ?
S4	1378490	IC=(H01L) OR MC=(L04-C? OR L04-F01? OR U11-D? OR U11-E?)
S5	18947	S1 AND S2 AND S3
S6	6797	S1 AND S2 AND S3 AND S4
S7	20444	WIREBOND? OR WIRE(W) BOND????
S8	126	S6 AND S7
S9	44329	EQUIAREA? OR (SAME OR EQUAL OR SIMILAR?) (2N) (AREA? OR SIZE?)
S10	2	S8 AND S9
S11	18075	BOND? (2N) PAD? ?
S12	5	S6 AND S11 AND S9 NOT S10

File 342:Derwent Patents Citation Indx 1978-04/200465

(c) 2004 Thomson Derwent

[illegible]

? map pn t ex

1 PN=US 2003042615

1 PN=US 6777789

2 PN=US 2003042615 + PN=US 6777789

S2 2 Serial: TD447

? map ct t ex /pn=

S3 250 Serial: TD467

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? map anpr t s3
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File 350:Derwent WPIX 1963-2004/UD,UM &UP=200469

(c) 2004 Thomson Derwent

Set	Items	Description
S1	848	Serial: <u>TD467</u>
S2	120612	MULTILAYER???? OR (MULTI???? OR STACK???) (2W) (LAYER???? OR LEVEL? ? OR CHIP? ? OR PACKAG???? OR TIER???? OR DIE OR DIES - OR DICE) OR MULTILEVEL? ? OR MULTIPACKAG???? OR MCM OR MULTICHIP???????? OR SCSP OR CSP OR CSPS OR PIGGYBACK???? OR...
S3	1592921	NM OR ANG OR ANG5 OR ANGST? OR THICK? OR THIN? OR MICRON? - OR MU OR MUM OR MILLIMICRO? OR MMU OR DIMEN? OR DISTANCE? OR - AA OR NANOMET? OR ULTRATHIN? OR SUPERTHIN? OR VERYTHIN? OR NA-NOTHICK?
S4	1839979	INSULAT????? OR ADHESIV????? OR SPACE??????? OR SPACING? ? - OR SPACERLESS? OR GAP? ?
S5	787479	IC=(H01L) OR MC=(L04-C? OR L04-F01? OR U11-D? OR U11-E?)
S6	9	S1 AND S2 AND S3 AND S4 AND S5

SET ABB=ON PLU=ON

INDEX 'HCAPLUS, INSPEC, COMPENDEX, SCISEARCH, PASCAL, ELCOM, ENERGY,
AEROSPACE, DISSABS, METADEX, ANTE, NTIS, CEABA-VTB, CONFSCI, EMA, ENTEC,
FEDRIP, RDISCLOSURE, SIGLE, SOLIDSTATE' ENTERED AT 15:09:38 ON 01 NOV 2004

L1 QUE MULTILAYER#### OR (MULTI#### OR STACK###) (2W) (LAYER#### OR LEVEL#
OR CHIP# OR PACKAG#### OR TIER#### OR DIE OR DIES OR DICE) OR
MULTILEVEL# OR MULTIPACKAG#### OR MCM OR MULTICHIP##### OR SCSP OR
CSP OR CSPS OR PIGGYBACK#### OR MCM OR MCMS
L2 QUE NM OR ANG OR ANGST? OR THICK? OR THIN? OR MICRON? OR MU OR MUM OR
MILLIMICRO? OR MMU OR DIMEN? OR DISTANCE? OR AA OR NANOMET? OR
ULTRATHIN? OR SUPERTHIN? OR VERYTHIN? OR NANOTHICK?
L3 QUE INSULAT##### OR ADHESIV##### OR SPACE##### OR SPACING# OR
SPACERLESS? OR GAP#
L4 QUE EQUIAREA? OR (SAME OR EQUAL OR SIMILAR? OR EQUI) (2N) (AREA? OR
SIZE?)
L5 QUE WIREBOND? OR WIRE(W) BOND####
L6 QUE L1 AND L2 AND L3 AND L4 AND L5
L7 QUE L1 AND L2 AND L3 AND L4
L8 QUE IC OR ICS OR ((INTEGRATED OR LOGIC) (W) (CIRCUIT#)) OR
(MICRO) (W) (ELECTRONIC? OR CIRCUIT# OR CHIP#) OR CHIP# OR MICROCIRCUIT#
OR DIE# OR WAFER# OR MICROELECTRONIC OR DICE OR SEMICONDUCT#### OR
SEMI(W) CONDUCT? OR (B2220 OR B2570)/CC OR FLIPCHIP#
L9 QUE L7 AND L8
L10 QUE L2(3N) L3 AND L7

FILE 'INSPEC, SCISEARCH, RDISCLOSURE, HCAPLUS, PASCAL, COMPENDEX,
AEROSPACE, ELCOM, DISSABS' ENTERED AT 15:30:53 ON 01 NOV 2004

L11 59 S L9
L12 25 S L10
L13 40 S L11 NOT P/DT NOT PY>2001
L14 8 S L12 NOT P/DT NOT PY>2001
L15 28 DUP REM L13 L14 (20 DUPLICATES REMOVED)
L16 10 S (L11 OR L12) AND P/DT
L17 10 DUP REM L16 (0 DUPLICATES REMOVED)